



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20190116000.1
Qualification of ASEN as Additional Assembly and Test Site
for Select WSON Package Devices
Change Notification / Sample Request

Date: February 01, 2019
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN ww admin team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team
SC Business Services

20190116000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

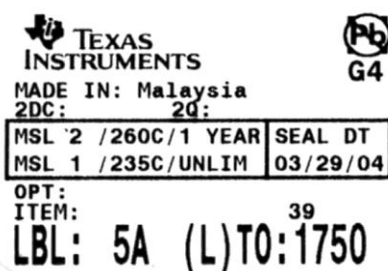
DEVICE	CUSTOMER PART NUMBER
CSD16301Q2	null
CSD17313Q2T	null
CSD85301Q2T	null
CSD87502Q2T	null
CSD17313Q2	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190116000.1			PCN Date:	Feb. 1, 2019												
Title:	Qualification of ASEN as Additional Assembly and Test Site for Select WSON Package Devices																
Customer Contact:	PCN Manager	Dept:	Quality Services														
Proposed 1st Ship Date:	May 1, 2019		Estimated Sample Availability:	Date Provided at Sample request													
Change Type:																	
☒	Assembly Site	☐	Design	☐	Wafer Bump Site												
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material												
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process												
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site												
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials												
		☐		☐	Wafer Fab Process												
PCN Details																	
Description of Change:																	
Texas Instruments Incorporated is announcing the qualification of ASEN as Additional Assembly and Test Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>UNIAT</td> <td>UNM</td> <td>MY</td> <td>Ipoh</td> </tr> <tr> <td>ASEN</td> <td>ASN</td> <td>CN</td> <td>Suzhou</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	UNIAT	UNM	MY	Ipoh	ASEN	ASN	CN	Suzhou
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City														
UNIAT	UNM	MY	Ipoh														
ASEN	ASN	CN	Suzhou														
Material Differences:																	
Group 1 Device:																	
	UNIAT	ASEN															
Mount Compound	47000011	1400410101															
Mold Compound	47160091	1800558151															
Wire Type	Au	Cu															
Lead finish	Matte Sn	NiPdAu															
Group 2 Device:																	
	UNIAT	ASEN															
Mount Compound	47000011	1400410101															
Mold Compound	47160155	1800558151															
Lead finish	Matte Sn	NiPdAu															
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																	
Reason for Change:																	
Continuity of supply.																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Anticipated impact on Material Declaration																	
☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.														
Changes to product identification resulting from this PCN:																	

Assembly Site		
UNIAT	Assembly Site Origin (22L)	ASO: UNM
ASEN	Assembly Site Origin (22L)	ASO: ASN

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected Group 1:

CSD16301Q2	CSD17313Q2	CSD17313Q2T
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Product Affected Group 2:

CSD85301Q2	CSD85301Q2T	CSD87502Q2	CSD87502Q2T
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Qualification Report

Q2 Package offload to ASEN - Phase 2 Dual die
Approved Date 12-Dec-2018

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CSD85301Q2	Qual Device: CSD87502Q2	Qual Device: CSD58902Q2	Qual Device: CSD87502Q2
HTGB	High Temp. Gate Bias, 150C	1000 Hours	-	-	1/77/0	1/77/0
HTRB	High Temp. Reverse Bias, 150C	1000 Hours	-	-	1/77/0	1/77/0
IOL	IOL 2min Cycle	10000 Cycles	-	3/231/0	-	-
AC	Autoclave 121C	96 Hours	-	3/231/0	-	-
HBM	ESD - HBM	400 V	-	-	1/3/0	-
CDM	ESD - CDM	2000 V	-	-	1/3/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	3/30/0	-	-
SD	Solderability	8 Hours Steam Age, Pb-Free	-	-	3/30/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0	-	-
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	3/231/0	-	-
WBP	Bond Pull	76 Wires, 5units min	-	3/228/0	-	-
WBS	Ball Bond Shear	76 balls, 5 units min	-	3/228/0	-	-
YLD	FTY and Bin Summary	-	1/Pass	3/Pass	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/llds/ti/legal/termsofsale.page>"

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com